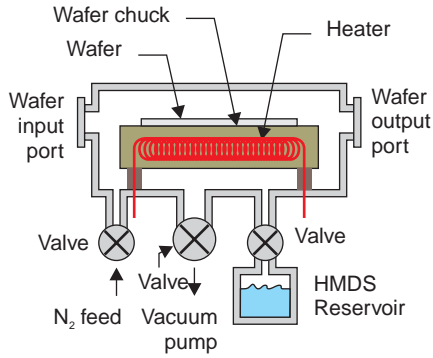
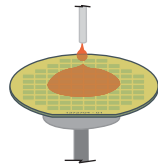


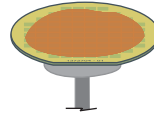
DUV Photolithography Process



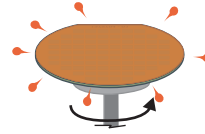
1) Surface Prime



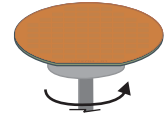
Dispense a controlled amount of photoresist



Allow the photoresist to spread across the wafer

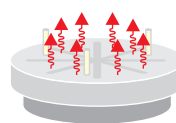


Rapidly ramp - up the coater spin speed throwing off excess photoresist

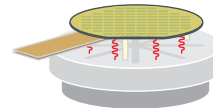


Spin at high speed to form a thin dry film of photoresist

2) Coat



Hot chuck with lift pins "up"



Wafer loaded onto lift pins

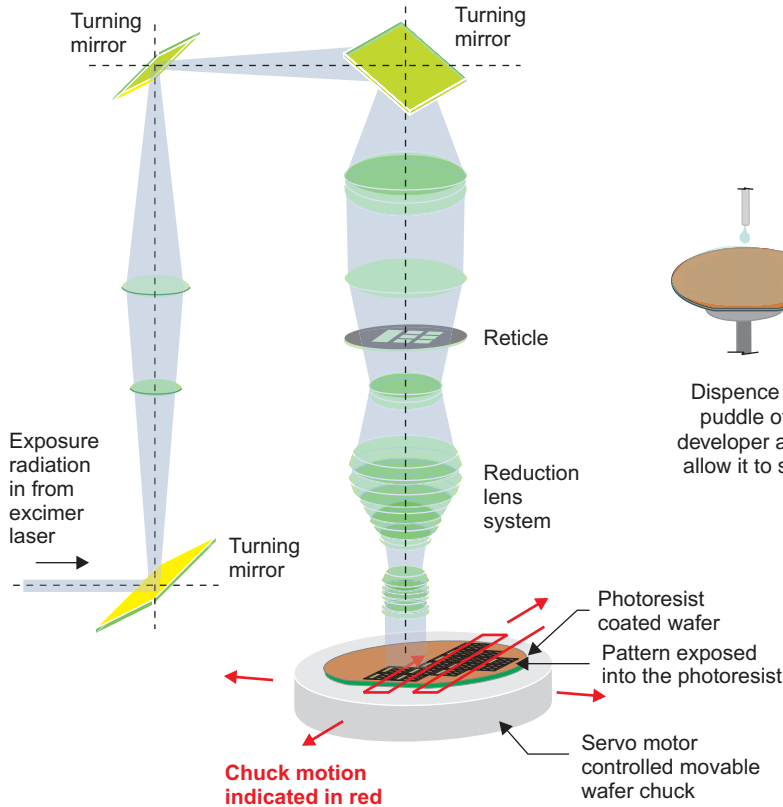


Lift pins down, wafer is baking

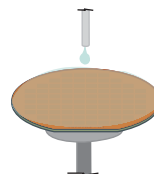
3) Pre-bake

5) Post Exposure Bake

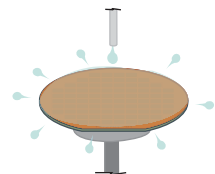
7) Hard Bake



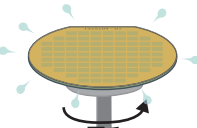
4) Expose



Dispense a puddle of developer and allow it to sit.



Dispense a rinse solution while slowly spinning the wafer.



Ramp up to high speed and spin the wafer dry.

6) Develop